

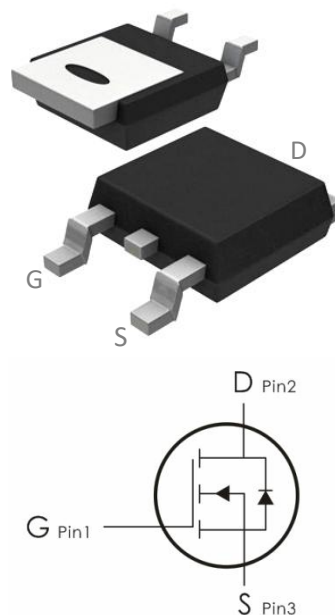
Description:

This N-Channel MOSFET uses advanced trench technology and design to provide excellent $R_{DS(on)}$ with low gate charge.

It can be used in a wide variety of applications.

Features:

- 1) $V_{DS}=20V, I_D=85A, R_{DS(on)} < 3.5m\Omega @ V_{GS}=4.5V$ (Typ: $2.8m\Omega$)
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra low $R_{DS(on)}$.
- 5) Excellent package for good heat dissipation.
- 6) MSL3



Package Marking and Ordering Information:

Part NO.	Marking	Package	Packing
DOD85N02	85N02	TO- 252	2500 pcs/Reel

Absolute Maximum Ratings: ($T_C=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 12	V
I_D	Continuous Drain Current ¹	85	A
	Continuous Drain Current- $T_C=100^{\circ}C$ ¹	59.8	
I_{DM}	Pulsed Drain Current ²	340	
P_D	Power Dissipation	47	W
E_{AS}	Single pulse avalanche energy ³	133	mJ
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55-+150	$^{\circ}C$

Thermal Characteristics:

Symbol	Parameter	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case	2.63	$^{\circ}C/W$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	62	$^{\circ}C/W$

Electrical Characteristics: ($T_C=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV _{DSS}	Drain-Sourctce Breakdown Voltage	V _{GS} =0V, I _D =250 μ A	20	---	---	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{GS} =0V, V _{DS} =20V	---	---	1	μ A
I _{GSS}	Gate-Source Leakage Current	V _{GS} =± 12V, V _{DS} =0A	---	---	± 100	nA
On Characteristics						
V _{GS(th)}	Gate-Source Threshold Voltage	V _{GS} =V _{DS} , I _D =250 μ A	0.6	0.75	0.9	V
R _{DS(ON)}	Drain-Source On Resistance ⁴	V _{GS} =4.5V, I _D =20A	---	2.8	3.5	m Ω
		V _{GS} =2.5V, I _D =10A	---	3.9	5	m Ω
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =10V, V _{GS} =0V, f=500KHz	---	3000	---	pF
C _{OSS}	Output Capacitance		---	420	--	
C _{rss}	Reverse Transfer Capacitance		---	393	---	
Switching Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{DS} =15V, I _D =15A, R _{ENG} =2.5 Ω ,V _{GS} =4.5V	---	16	---	ns
t _r	Rise Time		---	33	---	ns
t _{d(off)}	Turn-Off Delay Time		---	86	---	ns
t _f	Fall Time		---	136	---	ns
Q _g	Total Gate Charge	V _{GS} =10V, V _{DS} =10V, I _D =50A	---	38	---	nC
Q _{gs}	Gate-Source Charge		---	6.5	---	nC
Q _{gd}	Gate-Drain “Miller” Charge		---	21	---	nC
Drain-Source Diode Characteristics						
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _{SD} =50A	---	0.8	---	V
I _S	Continuous Drain Curren	V _D =V _G =0V	---	---	85	A
I _{SM}	Pulsed Drain Current		---	---	340	A
T _{rr}	Reverse Recovery Time	I _F =15A, T _J =25 °C	---	50	---	ns
Q _{rr}	Reverse Recovery Charge	dI/dt=100A/us	---	0.04	---	μ C

Notes:

1. Computed continuous current assumes the condition of $T_{j,Max}$ while the actual continuous current depends on the thermal & electro-mechanical application board design
2. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
3. EAS condition : $T_J=25^{\circ}C$, $V_{DD}=10V$, $V_G=4.5V$, $L=0.5mH$
4. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 0.5\%$

Typical Characteristics: ($T_C=25^{\circ}C$ unless otherwise noted)

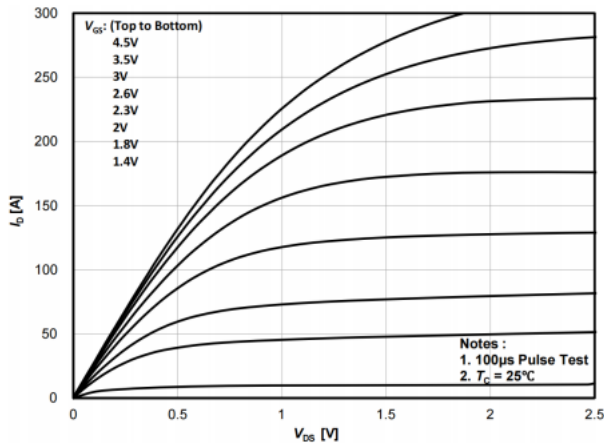


Figure 1. On-Region Characteristics

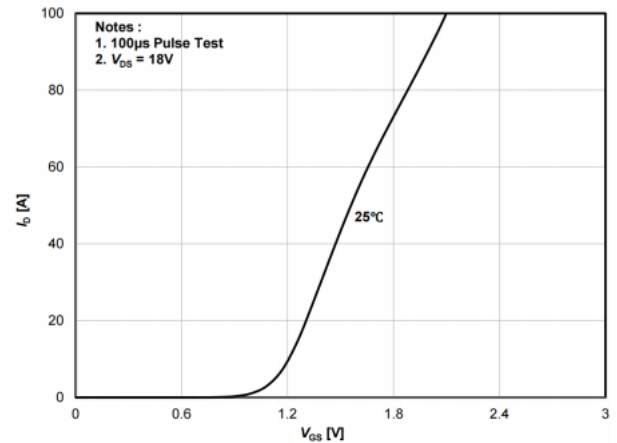


Figure 2. Transfer Characteristics

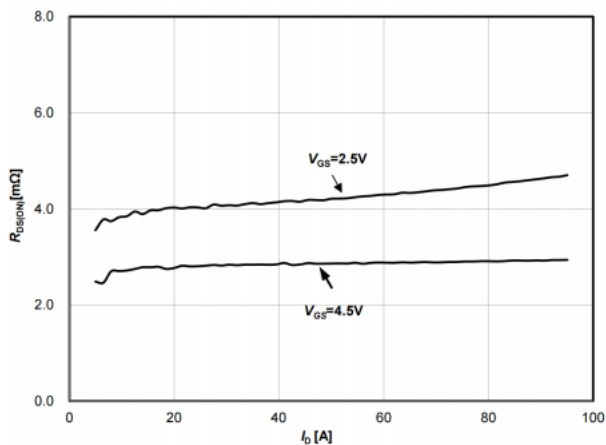


Figure 3. On Resistance vs. Drain Current

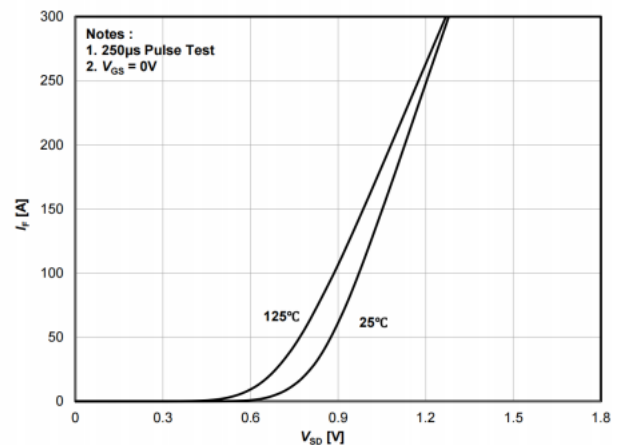


Figure 4. Diode Forward Voltage vs. Current

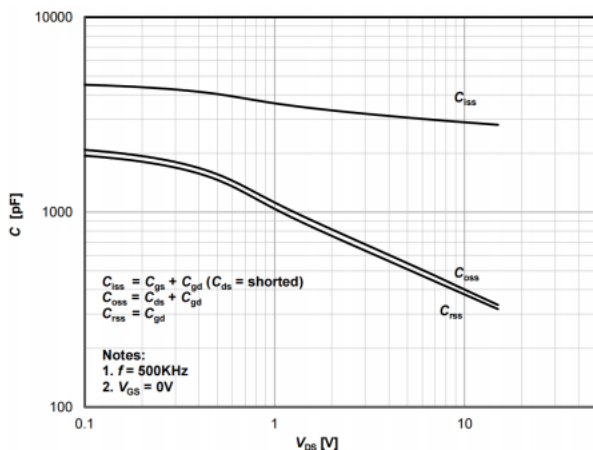


Figure 5. Capacitance Characteristics

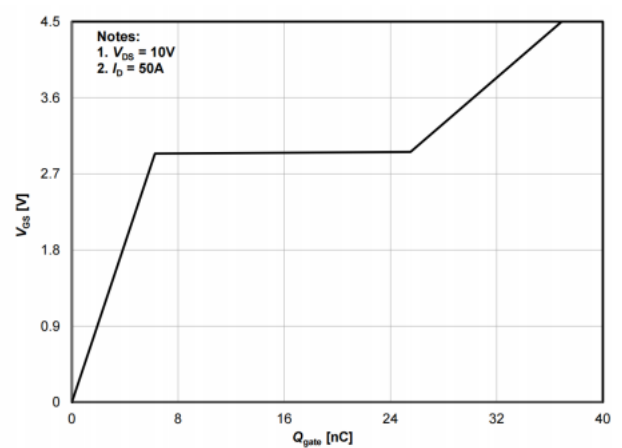


Figure 6. Gate Charge Characteristics

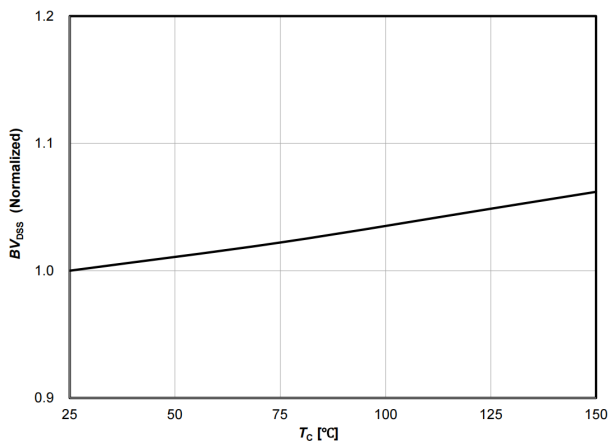


Figure 7. Normalized BV_{DSS} vs. Temperature

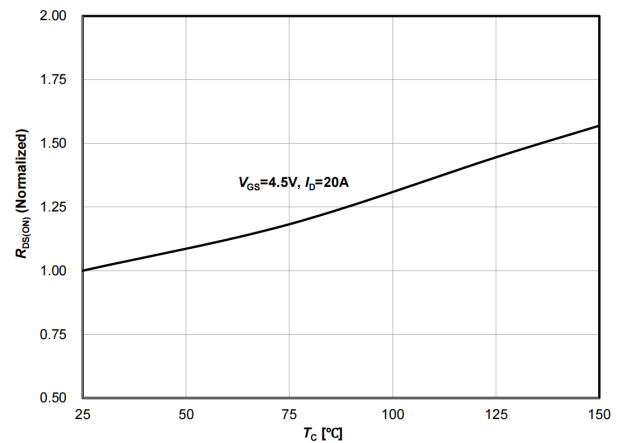


Figure 8. Normalized On-Resistance Variation vs. Temperature

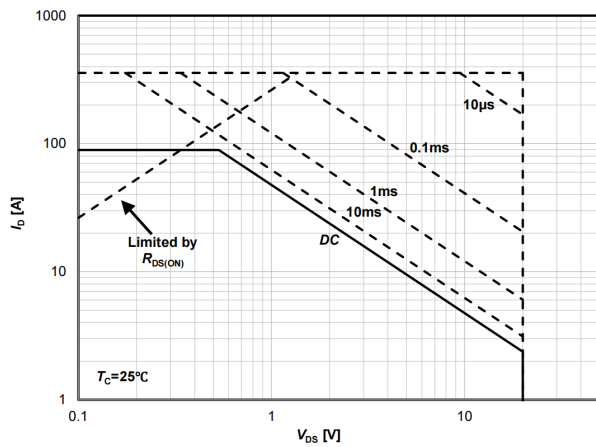


Figure 9. Safe Operating Area ³⁾

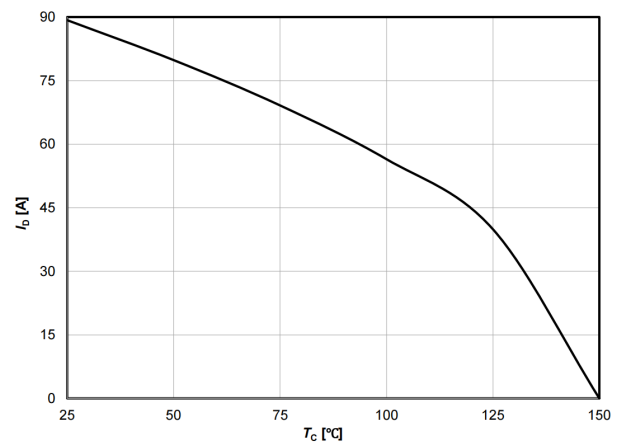


Figure 10. Drain Current vs. Temperature

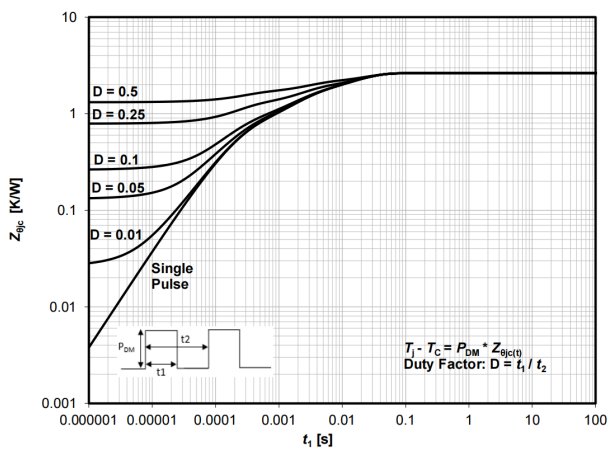
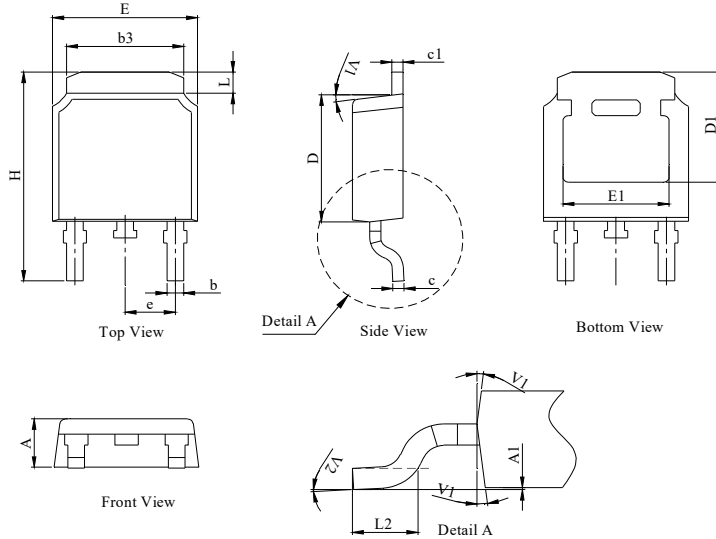


Figure 11. Transient Thermal Impedance

TO-252 Package Information

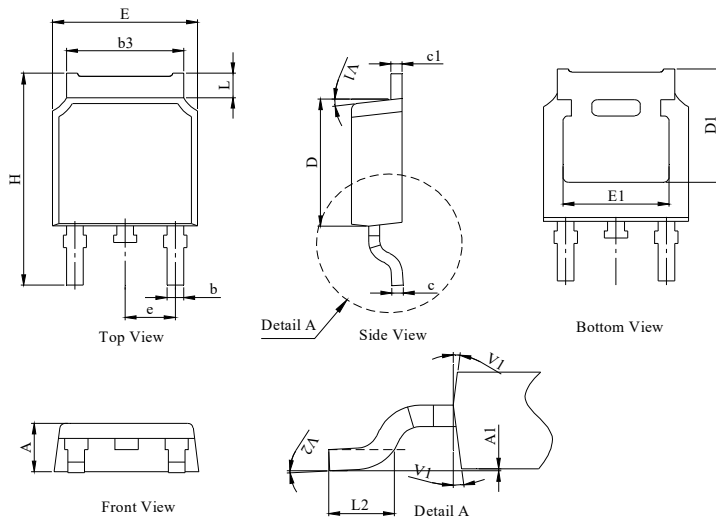
Package Outline Type-A

UNIT: mm



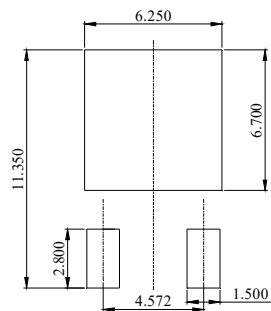
DIM.	MILLIMETER		
	MIN.	NOM.	MAX.
A	2.18	2.30	2.39
A1	0	--	0.13
b	0.64	0.76	0.89
c	0.40	0.50	0.61
c1	0.46	0.50	0.58
D	5.97	6.10	6.23
D1	5.05	--	--
E	6.35	6.60	6.73
E1	4.32	--	--
b3	5.21	5.38	5.55
e	2.29 BSC		
H	9.40	10.00	10.40
L	0.89	--	1.27
L2	1.40	--	1.78
V1	7° REF		
V2	0°	--	6°

Package Outline Type-B



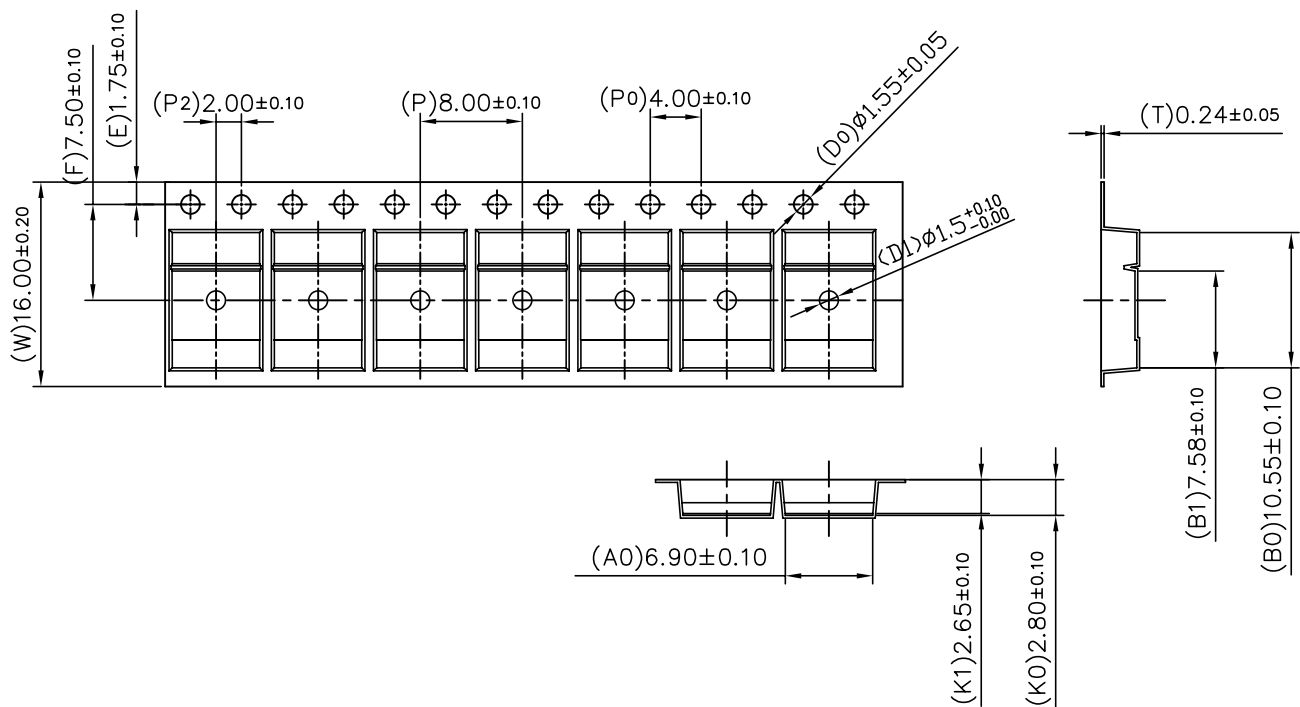
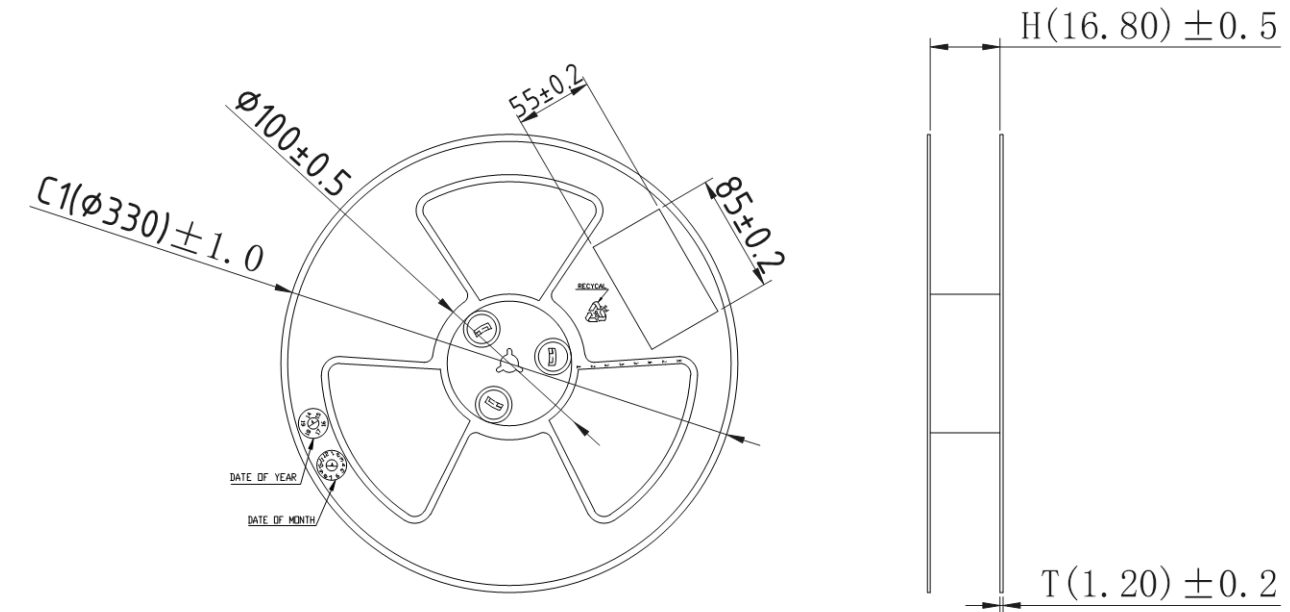
DIM.	MILLIMETER		
	MIN.	NOM.	MAX.
A	2.10	2.30	2.40
A1	0	--	0.13
b	0.66	0.76	0.86
b3	5.21	5.38	5.55
c	0.40	0.50	0.60
c1	0.44	0.50	0.58
D	5.90	6.10	6.30
D1	5.30REF		
E	6.40	6.60	6.80
E1	4.63	-	-
e	2.29 BSC		
H	9.50	10.00	10.70
L	1.09	--	1.21
L2	1.35	--	1.65
V1	7° REF		
V2	0°	--	6°

Recommended Soldering Footprint



Tape & Reel Information

Dimensions in mm



Pulling direction →

Marking Information:

①. Doingter LOGO

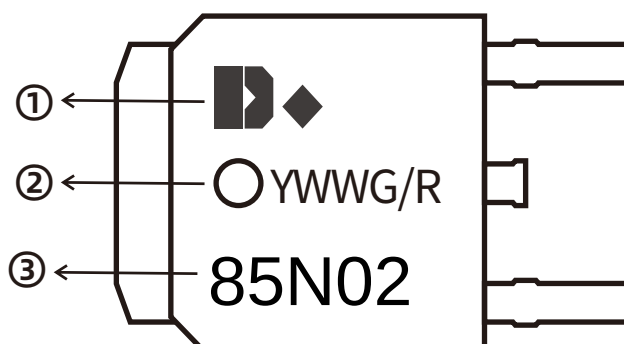
②. Date Code(YWWG / R)

Y : Year Code , last digit of the year

WW : Week Code(01-53)

G/R : G(Green) /R(Lead Free)

③. Part NO.



Previous Version

Version	Date	Subjects (major changes since last revision)
1.0	2025-04-01	Release of final version

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